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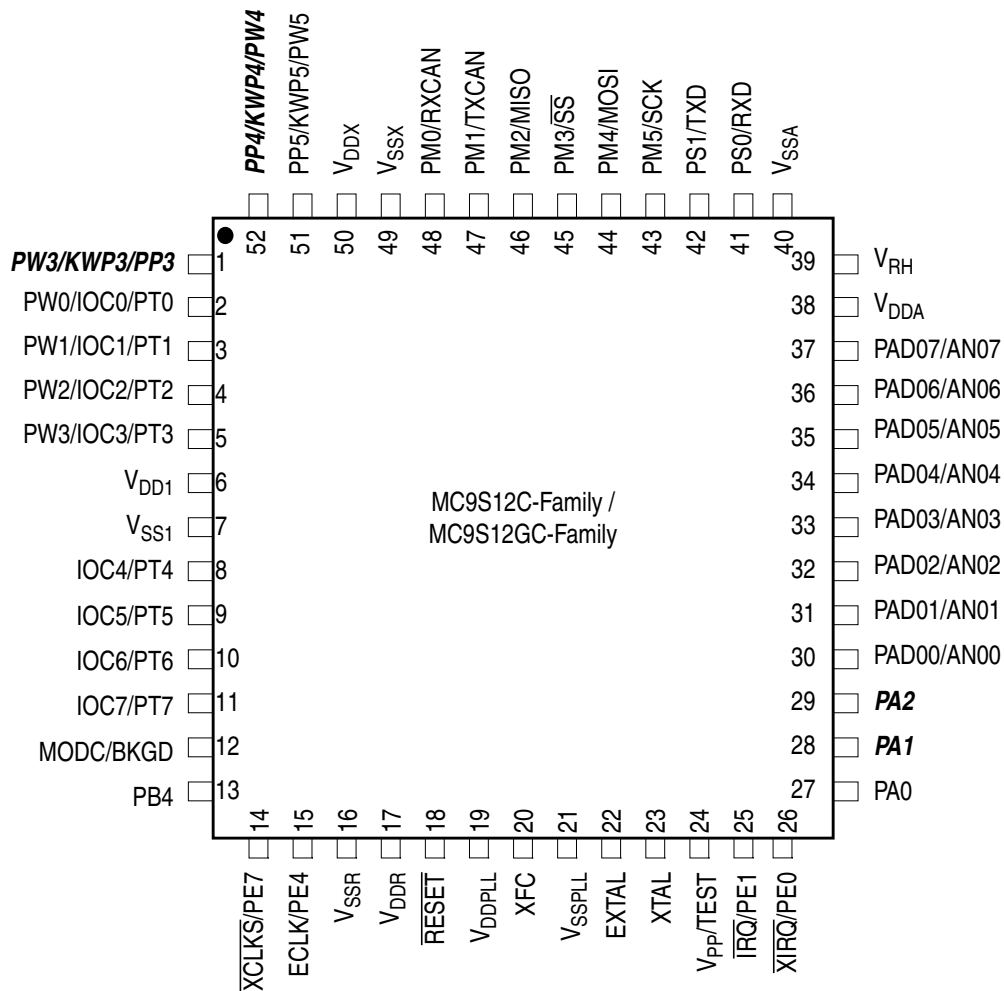
What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	EBI/EMI, SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	60
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s12gc64cfue



* Signals shown in ***Bold italic*** are not available on the 48-pin package

Figure 1-8. Pin Assignments in 52-Pin LQFP

Table 1-7. Mode Selection

BKGD = MODC	PE6 = MODB	PE5 = MODA	PP6 = ROMCTL	ROMON Bit	Mode Description
0	0	0	X	1	Special Single Chip, BDM allowed and ACTIVE. BDM is allowed in all other modes but a serial command is required to make BDM active.
0	0	1	0	1	Emulation Expanded Narrow, BDM allowed
			1	0	
0	1	0	X	0	Special Test (Expanded Wide), BDM allowed
0	1	1	0	1	Emulation Expanded Wide, BDM allowed
			1	0	
1	0	0	X	1	Normal Single Chip, BDM allowed
1	0	1	0	0	Normal Expanded Narrow, BDM allowed
			1	1	
1	1	0	X	1	Peripheral; BDM allowed but bus operations would cause bus conflicts (must not be used)
1	1	1	0	0	Normal Expanded Wide, BDM allowed
			1	1	

For further explanation on the modes refer to the S12_MEBI block guide.

Table 1-8. Clock Selection Based on PE7

PE7 = XCLKS	Description
1	Colpitts Oscillator selected
0	Pierce Oscillator/external clock selected

1.5.2 Security

The device will make available a security feature preventing the unauthorized read and write of the memory contents. This feature allows:

- Protection of the contents of FLASH,
- Operation in single-chip mode,
- Operation from external memory with internal FLASH disabled.

The user must be reminded that part of the security must lie with the user's code. An extreme example would be user's code that dumps the contents of the internal program. This code would defeat the purpose of security. At the same time the user may also wish to put a back door in the user's program. An example of this is the user downloads a key through the SCI which allows access to a programming routine that updates parameters.

1.5.2.1 Securing the Microcontroller

Once the user has programmed the FLASH, the part can be secured by programming the security bits located in the FLASH module. These non-volatile bits will keep the part secured through resetting the part and through powering down the part.

2.4.2.5 Port P

The PWM module is connected to port P. Port P pins can be used as PWM outputs. Further the Keypad Wake-Up function is implemented on pins PP[7:0]. During reset, port P pins are configured as high-impedance inputs.

Port P offers 8 general purpose I/O pins with edge triggered interrupt capability in wired-or fashion. The interrupt enable as well as the sensitivity to rising or falling edges can be individually configured on per pin basis. All 8 bits/pins share the same interrupt vector. Interrupts can be used with the pins configured as inputs or outputs.

An interrupt is generated when a bit in the port interrupt flag register and its corresponding port interrupt enable bit are both set. This external interrupt feature is capable to wake up the CPU when it is in STOP or WAIT mode.

A digital filter on each pin prevents pulses (Figure 2-48) shorter than a specified time from generating an interrupt. The minimum time varies over process conditions, temperature and voltage (Figure 2-47 and Table 2-38).

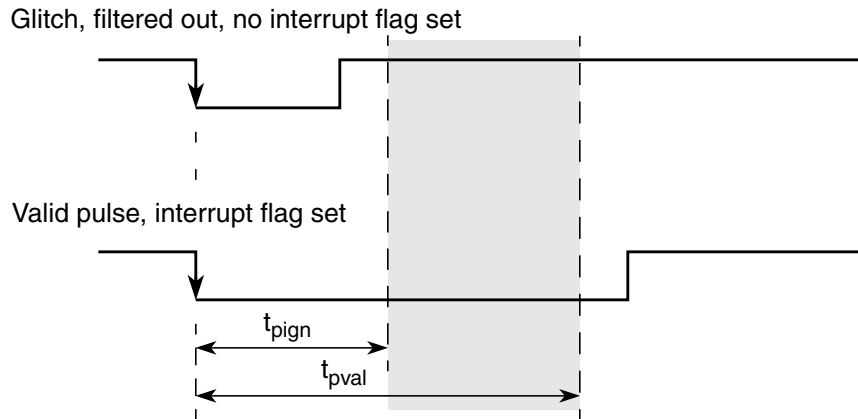


Figure 2-47. Interrupt Glitch Filter on Port P and J (PPS = 0)

Table 2-38. Pulse Detection Criteria

Pulse	STOP Mode		STOP ⁽¹⁾ Mode	
	Value	Unit	Value	Unit
Ignored	$t_{pign} \leq 3$	Bus clocks	$t_{pign} \leq 3.2$	μs
Uncertain	$3 < t_{pulse} < 4$	Bus clocks	$3.2 < t_{pulse} < 10$	μs
Valid	$t_{pval} \geq 4$	Bus clocks	$t_{pval} \geq 10$	μs

1. These values include the spread of the oscillator frequency over temperature, voltage and process.

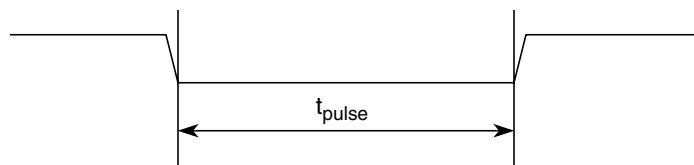


Figure 2-48. Pulse Illustration

3.1.1 Features

- Registers for mapping of address space for on-chip RAM, EEPROM, and FLASH (or ROM) memory blocks and associated registers
- Memory mapping control and selection based upon address decode and system operating mode
- Core address bus control
- Core data bus control and multiplexing
- Core security state decoding
- Emulation chip select signal generation (\overline{ECS})
- External chip select signal generation (\overline{XCS})
- Internal memory expansion
- External stretch and ROM mapping control functions via the MISC register
- Reserved registers for test purposes
- Configurable system memory options defined at integration of core into the system-on-a-chip (SoC).

3.1.2 Modes of Operation

Some of the registers operate differently depending on the mode of operation (i.e., normal expanded wide, special single chip, etc.). This is best understood from the register descriptions.

3.2 External Signal Description

All interfacing with the MMC sub-block is done within the core, it has no external signals.

3.3 Memory Map and Register Definition

A summary of the registers associated with the MMC sub-block is shown in [Figure 3-2](#). Detailed descriptions of the registers and bits are given in the subsections that follow.

3.3.1 Module Memory Map

Table 3-1. MMC Memory Map

Address Offset	Register	Access
0x0010	Initialization of Internal RAM Position Register (INITRM)	R/W
0x0011	Initialization of Internal Registers Position Register (INITRG)	R/W
0x0012	Initialization of Internal EEPROM Position Register (INITEE)	R/W
0x0013	Miscellaneous System Control Register (MISC)	R/W
0x0014	Reserved	—
⋮	⋮	—

vector spaces, expansion windows, and on-chip memory are mapped so that their address ranges do not overlap. The MMC will make only one select signal active at any given time. This activation is based upon the priority outlined in [Table 3-15](#). If two or more blocks share the same address space, only the select signal for the block with the highest priority will become active. An example of this is if the registers and the RAM are mapped to the same space, the registers will have priority over the RAM and the portion of RAM mapped in this shared space will not be accessible. The expansion windows have the lowest priority. This means that registers, vectors, and on-chip memory are always visible to a program regardless of the values in the page select registers.

Table 3-15. Select Signal Priority

Priority	Address Space
Highest	BDM (internal to core) firmware or register space
...	Internal register space
...	RAM memory block
...	EEPROM memory block
...	On-chip FLASH or ROM
Lowest	Remaining external space

In expanded modes, all address space not used by internal resources is by default external memory space. The data registers and data direction registers for ports A and B are removed from the on-chip memory map and become external accesses. If the EME bit in the MODE register (see MEBI block description chapter) is set, the data and data direction registers for port E are also removed from the on-chip memory map and become external accesses.

In special peripheral mode, the first 16 registers associated with bus expansion are removed from the on-chip memory map (PORTA, PORTB, DDRA, DDRB, PORTE, DDRE, PEAR, MODE, PUCR, RDRIV, and the EBI reserved registers).

In emulation modes, if the EMK bit in the MODE register (see MEBI block description chapter) is set, the data and data direction registers for port K are removed from the on-chip memory map and become external accesses.

3.4.2.2 Emulation Chip Select Signal

When the EMK bit in the MODE register (see MEBI block description chapter) is set, port K bit 7 is used as an active-low emulation chip select signal, \overline{ECS} . This signal is active when the system is in emulation mode, the EMK bit is set and the FLASH or ROM space is being addressed subject to the conditions outlined in [Section 3.4.3.2, “Extended Address \(XAB19:14\) and ECS Signal Functionality.”](#) When the EMK bit is clear, this pin is used for general purpose I/O.

3.4.2.3 External Chip Select Signal

When the EMK bit in the MODE register (see MEBI block description chapter) is set, port K bit 6 is used as an active-low external chip select signal, \overline{XCS} . This signal is active only when the \overline{ECS} signal described above is not active and when the system is addressing the external address space. Accesses to

6.4 Functional Description

The BDM receives and executes commands from a host via a single wire serial interface. There are two types of BDM commands, namely, hardware commands and firmware commands.

Hardware commands are used to read and write target system memory locations and to enter active background debug mode, see [Section 6.4.3, “BDM Hardware Commands.”](#) Target system memory includes all memory that is accessible by the CPU.

Firmware commands are used to read and write CPU resources and to exit from active background debug mode, see [Section 6.4.4, “Standard BDM Firmware Commands.”](#) The CPU resources referred to are the accumulator (D), X index register (X), Y index register (Y), stack pointer (SP), and program counter (PC).

Hardware commands can be executed at any time and in any mode excluding a few exceptions as highlighted, see [Section 6.4.3, “BDM Hardware Commands.”](#) Firmware commands can only be executed when the system is in active background debug mode (BDM).

6.4.1 Security

If the user resets into special single-chip mode with the system secured, a secured mode BDM firmware lookup table is brought into the map overlapping a portion of the standard BDM firmware lookup table. The secure BDM firmware verifies that the on-chip EEPROM and FLASH EEPROM are erased. This being the case, the UNSEC bit will get set. The BDM program jumps to the start of the standard BDM firmware and the secured mode BDM firmware is turned off and all BDM commands are allowed. If the EEPROM or FLASH do not verify as erased, the BDM firmware sets the ENBDM bit, without asserting UNSEC, and the firmware enters a loop. This causes the BDM hardware commands to become enabled, but does not enable the firmware commands. This allows the BDM hardware to be used to erase the EEPROM and FLASH. After execution of the secure firmware, regardless of the results of the erase tests, the CPU registers, INITEE and PPAGE, will no longer be in their reset state.

6.4.2 Enabling and Activating BDM

The system must be in active BDM to execute standard BDM firmware commands. BDM can be activated only after being enabled. BDM is enabled by setting the ENBDM bit in the BDM status (BDMSTS) register. The ENBDM bit is set by writing to the BDM status (BDMSTS) register, via the single-wire interface, using a hardware command such as WRITE_BD_BYTE.

After being enabled, BDM is activated by one of the following¹:

- Hardware BACKGROUND command
- BDM external instruction tagging mechanism
- CPU BGND instruction
- Breakpoint sub-block’s force or tag mechanism²

When BDM is activated, the CPU finishes executing the current instruction and then begins executing the firmware in the standard BDM firmware lookup table. When BDM is activated by the breakpoint sub-

1. BDM is enabled and active immediately out of special single-chip reset.

2. This method is only available on systems that have a breakpoint or a debug sub-block.

of 4 OSCCLK plus 4 PLLCLK cycles to make the transition. During the transition, all clocks freeze and CPU activity ceases.

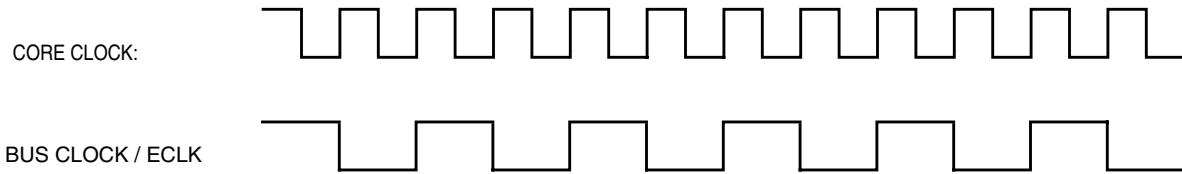


Figure 9-18. Core Clock and Bus Clock Relationship

9.4.3 Clock Monitor (CM)

If no OSCCLK edges are detected within a certain time, the clock monitor within the oscillator block generates a clock monitor fail event. The CRGV4 then asserts self-clock mode or generates a system reset depending on the state of SCME bit. If the clock monitor is disabled or the presence of clocks is detected no failure is indicated by the oscillator block. The clock monitor function is enabled/disabled by the CME control bit.

9.4.4 Clock Quality Checker

The clock monitor performs a coarse check on the incoming clock signal. The clock quality checker provides a more accurate check in addition to the clock monitor.

A clock quality check is triggered by any of the following events:

- Power-on reset (POR)
- Low voltage reset (LVR)
- Wake-up from full stop mode (exit full stop)
- Clock monitor fail indication (CM fail)

A time window of 50000 VCO clock cycles¹ is called *check window*.

A number greater equal than 4096 rising OSCCLK edges within a *check window* is called *osc ok*. Note that *osc ok* immediately terminates the current *check window*. See Figure 9-19 as an example.

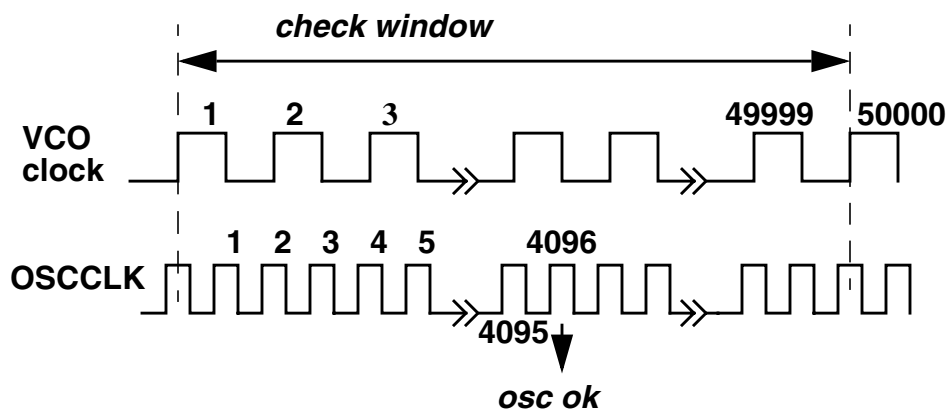


Figure 9-19. Check Window Example

1. VCO clock cycles are generated by the PLL when running at minimum frequency f_{SCM} .

Table 10-10. CANRIER Register Field Descriptions (continued)

Field	Description
1 OVRIE	Overrun Interrupt Enable 0 No interrupt request is generated from this event. 1 An overrun event causes an error interrupt request.
0 RXFIE	Receiver Full Interrupt Enable 0 No interrupt request is generated from this event. 1 A receive buffer full (successful message reception) event causes a receiver interrupt request.

1. WUPIE and WUPE (see Section 10.3.2.1, "MSCAN Control Register 0 (CANCTL0)") must both be enabled if the recovery mechanism from stop or wait is required.
2. Bus-off state is defined by the CAN standard (see Bosch CAN 2.0A/B protocol specification: for only transmitters. Because the only possible state change for the transmitter from bus-off to TxOK also forces the receiver to skip its current state to RxOK, the coding of the RXSTAT[1:0] flags define an additional bus-off state for the receiver (see Section 10.3.2.5, "MSCAN Receiver Flag Register (CANRFLG)").

10.3.2.7 MSCAN Transmitter Flag Register (CANTFLG)

The transmit buffer empty flags each have an associated interrupt enable bit in the CANTIER register.

Module Base + 0x0006

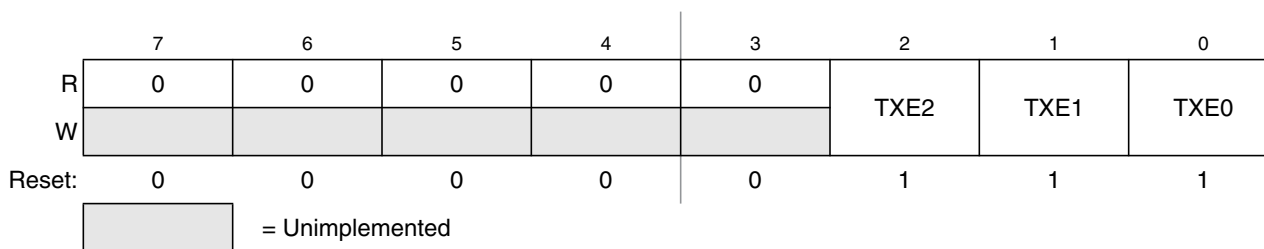


Figure 10-10. MSCAN Transmitter Flag Register (CANTFLG)

NOTE

The CANTFLG register is held in the reset state when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable when not in initialization mode (INITRQ = 0 and INITAK = 0).

Read: Anytime

Write: Anytime for TXEx flags when not in initialization mode; write of 1 clears flag, write of 0 is ignored



Figure 10-41. 8-bit Maskable Identifier Acceptance Filters

Table 12-2. PWME Field Descriptions (continued)

Field	Description
1 PWME1	Pulse Width Channel 1 Enable 0 Pulse width channel 1 is disabled. 1 Pulse width channel 1 is enabled. The pulse modulated signal becomes available at PWM, output bit 1 when its clock source begins its next cycle.
0 PWME0	Pulse Width Channel 0 Enable 0 Pulse width channel 0 is disabled. 1 Pulse width channel 0 is enabled. The pulse modulated signal becomes available at PWM, output bit 0 when its clock source begins its next cycle. If CON01 = 1, then bit has no effect and PWM output line 0 is disabled.

12.3.2.2 PWM Polarity Register (PWMPOL)

The starting polarity of each PWM channel waveform is determined by the associated PPOLx bit in the PWMPOL register. If the polarity bit is 1, the PWM channel output is high at the beginning of the cycle and then goes low when the duty count is reached. Conversely, if the polarity bit is 0 the output starts low and then goes high when the duty count is reached.

Module Base + 0x0001

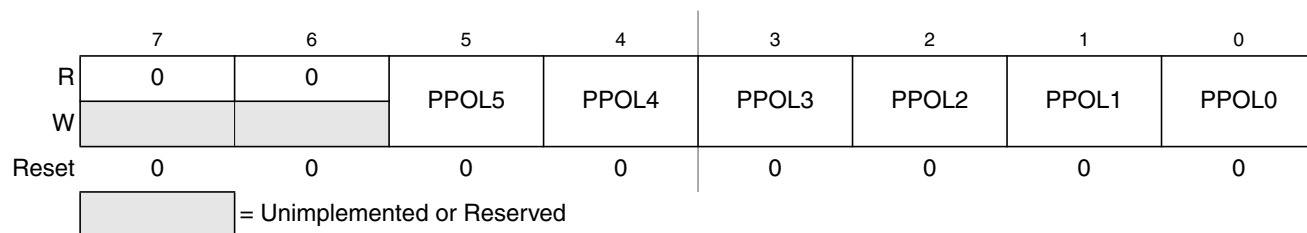


Figure 12-4. PWM Polarity Register (PWMPOL)

Read: anytime

Write: anytime

NOTE

PPOLx register bits can be written anytime. If the polarity is changed while a PWM signal is being generated, a truncated or stretched pulse can occur during the transition

Table 12-3. PWMPOL Field Descriptions

Field	Description
5 PPOL5	Pulse Width Channel 5 Polarity 0 PWM channel 5 output is low at the beginning of the period, then goes high when the duty count is reached. 1 PWM channel 5 output is high at the beginning of the period, then goes low when the duty count is reached.
4 PPOL4	Pulse Width Channel 4 Polarity 0 PWM channel 4 output is low at the beginning of the period, then goes high when the duty count is reached. 1 PWM channel 4 output is high at the beginning of the period, then goes low when the duty count is reached.

In Figure 13-14 the verification samples RT3 and RT5 determine that the first low detected was noise and not the beginning of a start bit. The RT clock is reset and the start bit search begins again. The noise flag is not set because the noise occurred before the start bit was found.

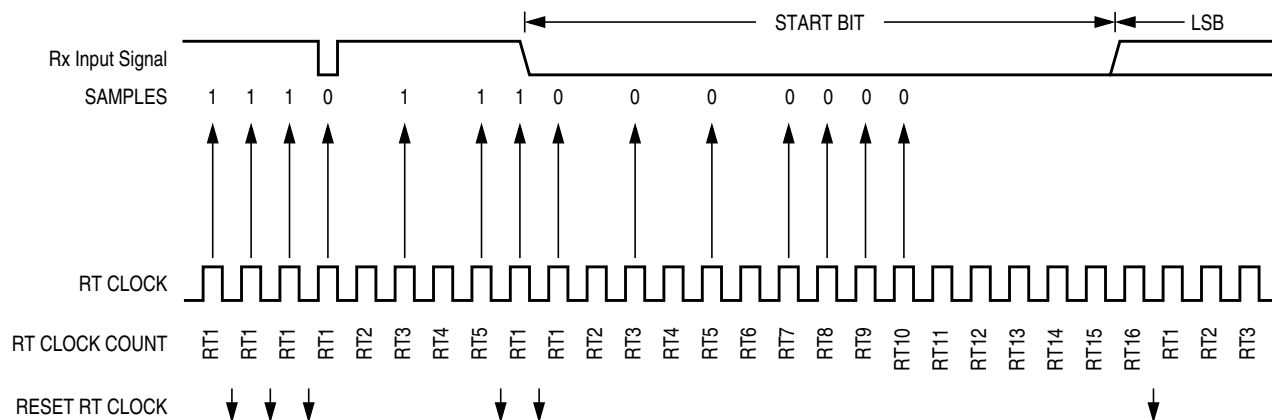


Figure 13-14. Start Bit Search Example 1

In Figure 13-15, verification sample at RT3 is high. The RT3 sample sets the noise flag. Although the perceived bit time is misaligned, the data samples RT8, RT9, and RT10 are within the bit time and data recovery is successful.

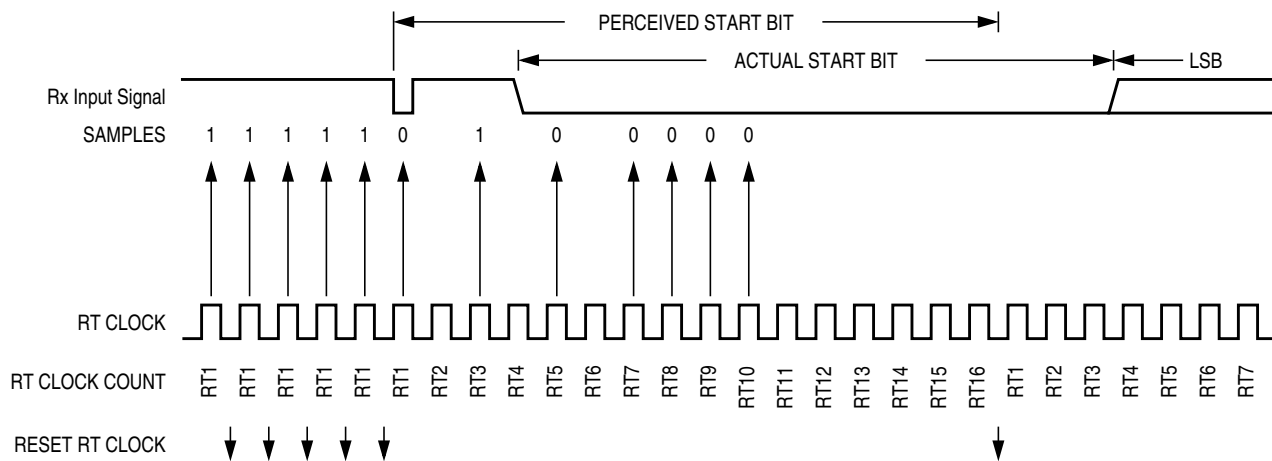


Figure 13-15. Start Bit Search Example 2

15.3.2.15 16-Bit Pulse Accumulator Control Register (PACTL)

Module Base + 0x0020

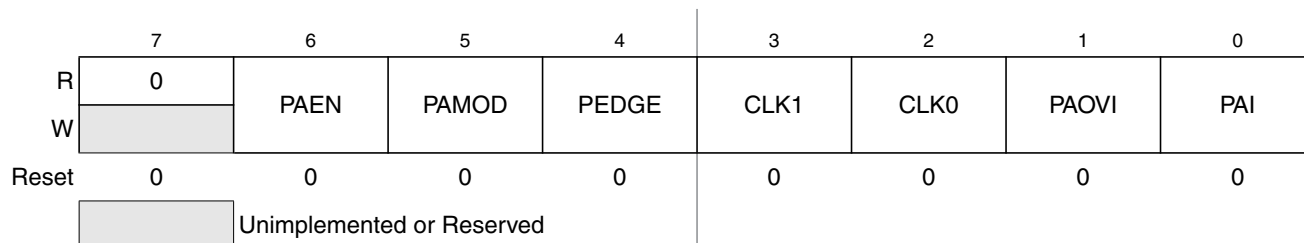


Figure 15-24. 16-Bit Pulse Accumulator Control Register (PACTL)

When PAEN is set, the PACT is enabled. The PACT shares the input pin with IOC7.

Read: Any time

Write: Any time

Table 15-19. PACTL Field Descriptions

Field	Description
6 PAEN	Pulse Accumulator System Enable — PAEN is independent from TEN. With timer disabled, the pulse accumulator can function unless pulse accumulator is disabled. 0 16-Bit Pulse Accumulator system disabled. 1 Pulse Accumulator system enabled.
5 PAMOD	Pulse Accumulator Mode — This bit is active only when the Pulse Accumulator is enabled (PAEN = 1). See Table 15-20 . 0 Event counter mode. 1 Gated time accumulation mode.
4 PEDGE	Pulse Accumulator Edge Control — This bit is active only when the Pulse Accumulator is enabled (PAEN = 1). For PAMOD bit = 0 (event counter mode). See Table 15-20 . 0 Falling edges on IOC7 pin cause the count to be incremented. 1 Rising edges on IOC7 pin cause the count to be incremented. For PAMOD bit = 1 (gated time accumulation mode). 0 IOC7 input pin high enables M (bus clock) divided by 64 clock to Pulse Accumulator and the trailing falling edge on IOC7 sets the PAIF flag. 1 IOC7 input pin low enables M (bus clock) divided by 64 clock to Pulse Accumulator and the trailing rising edge on IOC7 sets the PAIF flag.
3:2 CLK[1:0]	Clock Select Bits — Refer to Table 15-21 .
1 PAOVI	Pulse Accumulator Overflow Interrupt Enable 0 Interrupt inhibited. 1 Interrupt requested if PAOVF is set.
0 PAI	Pulse Accumulator Input Interrupt Enable 0 Interrupt inhibited. 1 Interrupt requested if PAIF is set.

18.4.2 Operating Modes

18.4.2.1 Wait Mode

If the MCU enters wait mode while a Flash command is active ($CCIF = 0$), that command and any buffered command will be completed.

The Flash module can recover the MCU from wait mode if the interrupts are enabled (see [Section 18.4.5](#)).

18.4.2.2 Stop Mode

If the MCU enters stop mode while a Flash command is active ($CCIF = 0$), that command will be aborted and the data being programmed or erased is lost. The high voltage circuitry to the Flash array will be switched off when entering stop mode. $CCIF$ and $ACCERR$ flags will be set. Upon exit from stop mode, the $CBEIF$ flag will be set and any buffered command will not be executed. The $ACCERR$ flag must be cleared before returning to normal operation.

NOTE

As active Flash commands are immediately aborted when the MCU enters stop mode, it is strongly recommended that the user does not use the STOP instruction during program and erase execution.

18.4.2.3 Background Debug Mode

In background debug mode (BDM), the FPROT register is writable. If the MCU is unsecured, then all Flash commands listed in [Table 18-16](#) can be executed. If the MCU is secured and is in special single chip mode, the only possible command to execute is mass erase.

18.4.3 Flash Module Security

The Flash module provides the necessary security information to the MCU. After each reset, the Flash module determines the security state of the MCU as defined in [Section 18.3.2.2](#), “Flash Security Register (FSEC)”.

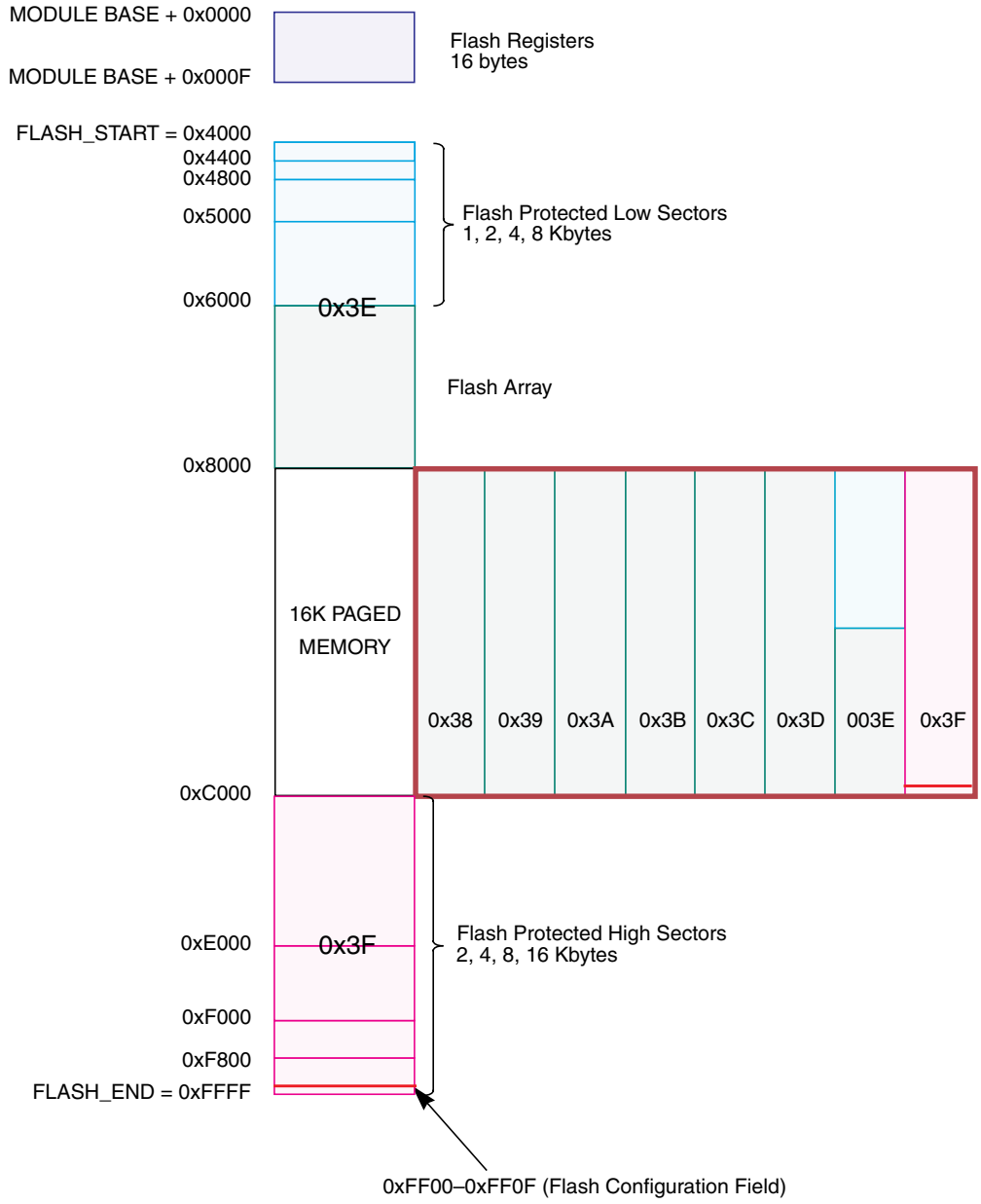
The contents of the Flash security/options byte at address 0xFF0F in the Flash configuration field must be changed directly by programming address 0xFF0F when the device is unsecured and the higher address sector is unprotected. If the Flash security/options byte is left in the secure state, any reset will cause the MCU to return to the secure operating mode.

18.4.3.1 Unsecuring the MCU using Backdoor Key Access

The MCU may only be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor key (four 16-bit words programmed at addresses 0xFF00–0xFF07). If $KEYEN[1:0] = 1:0$ and the $KEYACC$ bit is set, a write to a backdoor key address in the Flash array triggers a comparison between the written data and the backdoor key data stored in the Flash array. If all four words of data are written to the correct addresses in the correct order and the data matches the backdoor key stored in the Flash array, the MCU will be unsecured. The data must be written to the backdoor key



Figure 19-27. Example Sector Erase Command Flow



Note: 0x38-0x3F correspond to the PPAGE register content

Figure 20-3. Flash Memory Map

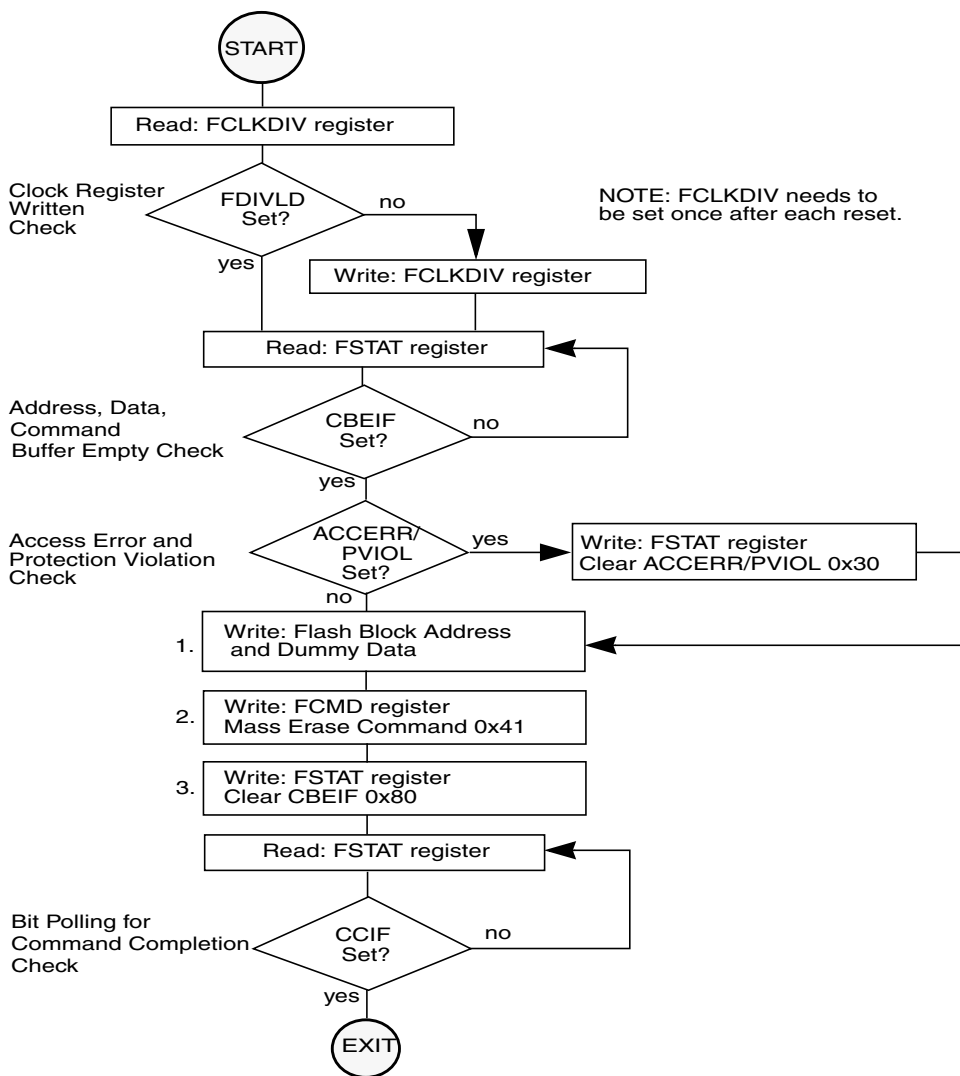


Figure 20-27. Example Mass Erase Command Flow

21.3.2.1 Flash Clock Divider Register (FCLKDIV)

The FCLKDIV register is used to control timed events in program and erase algorithms.

Module Base + 0x0000



Figure 21-4. Flash Clock Divider Register (FCLKDIV)

All bits in the FCLKDIV register are readable, bits 6–0 are write once and bit 7 is not writable.

Table 21-3. FCLKDIV Field Descriptions

Field	Description
7 FDIVLD	Clock Divider Loaded 0 FCLKDIV register has not been written 1 FCLKDIV register has been written to since the last reset
6 PRDIV8	Enable Prescaler by 8 0 The oscillator clock is directly fed into the Flash clock divider 1 The oscillator clock is divided by 8 before feeding into the Flash clock divider
5–0 FDIV[5:0]	Clock Divider Bits — The combination of PRDIV8 and FDIV[5:0] must divide the oscillator clock down to a frequency of 150 kHz – 200 kHz. The maximum divide ratio is 512. Refer to Section 21.4.1.1, “Writing the FCLKDIV Register” for more information.

21.3.2.2 Flash Security Register (FSEC)

The FSEC register holds all bits associated with the security of the MCU and Flash module.

Module Base + 0x0001

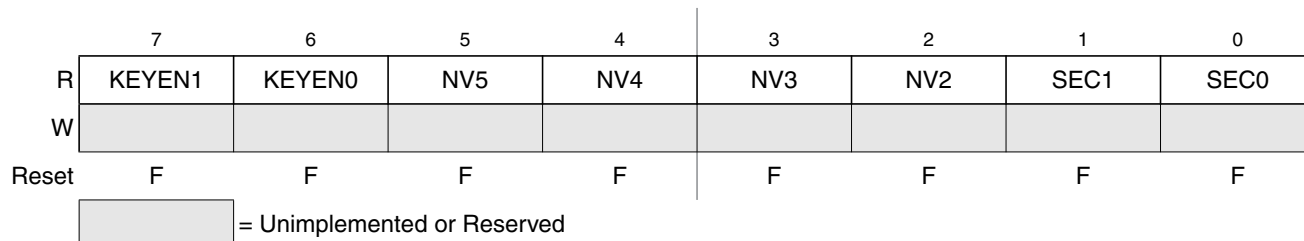


Figure 21-5. Flash Security Register (FSEC)

All bits in the FSEC register are readable but not writable.

The FSEC register is loaded from the Flash configuration field at 0xFF0F during the reset sequence, indicated by F in [Figure 21-5](#).

21.4.1.3 Valid Flash Commands

Table 21-16 summarizes the valid Flash commands along with the effects of the commands on the Flash array.

Table 21-16. Valid Flash Commands

FCMD	Meaning	Function on Flash Array
0x05	Erase Verify	Verify all bytes in the Flash array are erased. If the Flash array is erased, the BLANK bit will set in the FSTAT register upon command completion.
0x20	Program	Program a word (2 bytes) in the Flash array.
0x40	Sector Erase	Erase all 1024 bytes in a sector of the Flash array.
0x41	Mass Erase	Erase all bytes in the Flash array. A mass erase of the full Flash array is only possible when FPLDIS, FPHDIS, and FPOPEN bits in the FPROT register are set prior to launching the command.

CAUTION

A Flash word must be in the erased state before being programmed.
Cumulative programming of bits within a Flash word is not allowed.

injection current may flow out of V_{DD5} and could result in external power supply going out of regulation. Insure external V_{DD5} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power; e.g. if no system clock is present, or if clock rate is very low which would reduce overall power consumption.

A.1.5 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only. A functional operation under or outside those maxima is not guaranteed. Stress beyond those limits may affect the reliability or cause permanent damage of the device.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either V_{SS5} or V_{DD5}).

Table A-1. Absolute Maximum Ratings

Num	Rating	Symbol	Min	Max	Unit
1	I/O, Regulator and Analog Supply Voltage	V_{DD5}	-0.3	6.5	V
2	Digital Logic Supply Voltage ⁽¹⁾	V_{DD}	-0.3	3.0	V
3	PLL Supply Voltage ¹	V_{DDPLL}	-0.3	3.0	V
4	Voltage difference V_{DDX} to V_{DDR} and V_{DDA}	ΔV_{DDX}	-0.3	0.3	V
5	Voltage difference V_{SSX} to V_{SSR} and V_{SSA}	ΔV_{SSX}	-0.3	0.3	V
6	Digital I/O Input Voltage	V_{IN}	-0.3	6.5	V
7	Analog Reference	V_{RH}, V_{RL}	-0.3	6.5	V
8	XFC, EXTAL, XTAL inputs	V_{ILV}	-0.3	3.0	V
9	TEST input	V_{TEST}	-0.3	10.0	V
10	Instantaneous Maximum Current Single pin limit for all digital I/O pins ⁽²⁾	I_D	-25	+25	mA
11	Instantaneous Maximum Current Single pin limit for XFC, EXTAL, XTAL ⁽³⁾	I_{DL}	-25	+25	mA
12	Instantaneous Maximum Current Single pin limit for TEST ⁽⁴⁾	I_{DT}	-0.25	0	mA
13	Operating Temperature Range (packaged)	T_A	-40	125	°C
14	Operating Temperature Range (junction)	T_J	-40	140	°C
15	Storage Temperature Range	T_{stg}	-65	155	°C

1. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when the device is powered from an external source.

2. All digital I/O pins are internally clamped to V_{SSX} and V_{DDX} , V_{SSR} and V_{DDR} or V_{SSA} and V_{DDA} .

3. These pins are internally clamped to V_{SSPLL} and V_{DDPLL} .

4. This pin is clamped low to V_{SSX} , but not clamped high. This pin must be tied low in applications.

A.4.1.3 SRAM Data Retention

Provided an appropriate external reset signal is applied to the MCU, preventing the CPU from executing code when V_{DD5} is out of specification limits, the SRAM contents integrity is guaranteed if after the reset the PORF bit in the CRG Flags Register has not been set.

A.4.1.4 External Reset

When external reset is asserted for a time greater than PW_{RSTL} the CRG module generates an internal reset, and the CPU starts fetching the reset vector without doing a clock quality check, if there was an oscillation before reset.

A.4.1.5 Stop Recovery

Out of STOP the controller can be woken up by an external interrupt. A clock quality check as after POR is performed before releasing the clocks to the system.

A.4.1.6 Pseudo Stop and Wait Recovery

The recovery from Pseudo STOP and Wait are essentially the same since the oscillator was not stopped in both modes. In Pseudo Stop Mode the voltage regulator is switched to reduced performance mode to reduce power consumption. The returning out of pseudo stop to full performance takes t_{vup} . The controller can be woken up by internal or external interrupts. After t_{wrs} in Wait or $t_{vup} + t_{wrs}$ in Pseudo Stop the CPU starts fetching the interrupt vector.

A.4.2 Oscillator

The device features an internal Colpitts and Pierce oscillator. The selection of Colpitts oscillator or Pierce oscillator/external clock depends on the XCLKS signal which is sampled during reset. Pierce oscillator/external clock mode allows the input of a square wave. Before asserting the oscillator to the internal system clocks the quality of the oscillation is checked for each start from either power-on, STOP or oscillator fail. t_{CQOUT} specifies the maximum time before switching to the internal self clock mode after POR or STOP if a proper oscillation is not detected. The quality check also determines the minimum oscillator start-up time t_{UPOSC} . The device also features a clock monitor. A Clock Monitor Failure is asserted if the frequency of the incoming clock signal is below the Assert Frequency f_{CMFA} .